

Abstract of the Disclosure

Methods for producing a flip chip package by prepackaging one or more dice on a semiconductor wafer are provided. An embodiment of the method includes applying an adhesive to a first side of a finished wafer, where a number of dice are located. The
5 active layer of the dice is on the first side of the finished wafer. The method further includes forming an array of conductive elements within the adhesive, where the array of conductive elements is electrically coupled to an array of connection pads on a die. The wafer can be diced to provide pre-packaged chips. To provide greater mounting densities, two or more dice may be coupled before application of the adhesive layer.

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